



BZT52HC2V4WF - BZT52HC47WF

SURFACE MOUNT ZENER DIODE

Features

- Flat Lead Package Design for Low Profile and High Power Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOD123F (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Alloy Leadframe. Solderable per MIL-STD-202, Method 208 <a>®
- Polarity: Cathode Band
- Weight: 0.015 grams (Approximate)

SOD123F (Type B)





Top View

Bottom View

Ordering Information (Note 4)

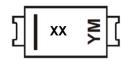
Ī	Part Number	Compliance	Case	Packaging
	(Type Number)-7*	AEC-Q101	SOD123F (Type B)	3,000/Tape & Reel

^{*}Add "-7" to the appropriate type number in Electrical Characteristics Table, example: 6.2V Zener = BZT52HC6V2WF-7.

Notes: 1. No purpos

- $1.\ No\ purposely\ added\ lead.\ Fully\ EU\ Directive\ 2002/95/EC\ (RoHS)\ \&\ 2011/65/EU\ (RoHS\ 2)\ compliant.$
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



XX = Product Type Marking Code (See Electrical Characteristics Table) YM = Date Code Marking Y = Year (ex: C = 2015)

M = Month (ex: 9 = September)

Date Code Key

Year Code		201	5	2016	20)17	2018	2	2019	2020		2021
		С		D	I	E	F		G	Н		I
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Forward Voltage (Note 5)	@ I _F = 10mA	V _F	0.9	V
Forward Current		l _F	250	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	375	mW
Power Dissipation (Note 7)	P _D	830	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{ heta JA}$	330	°C/W
Thermal Resistance, Junction to Ambient Air (Note 7)	$R_{ heta JA}$	150	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-65 to +150	°C

Note:

- 5. Short duration pulse test used to minimize self-heating effect.6. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com/package-outlines.html.

 7. Device mounted on FR-4 PCB with mounting pad for cathode 1cm².



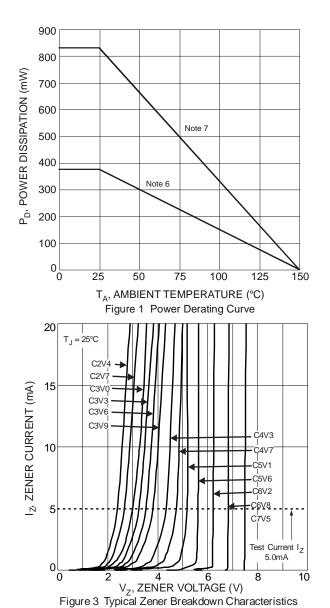
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

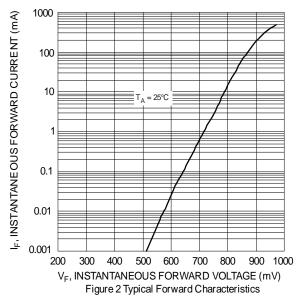
		Zener Voltage Range (Note 8)			Maximui	Maximum Zener Impedance (Note 9) Temperature Coefficient				Total Maximum Reverse Capacitance Current (Note 8)		erse rent
Type Number	Marking Codes	Vz @	⊉ I _{ZT}	I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	T _C (© I _{ZT}	C_T @ f = 1MHz, $V_R = 0V$	I _R	@ V _R
		Min (V)	Max (V)	mA	2	2	mA	Min (mV/°C)	Max (mV/°C)	Max (pF)	μΑ	V
BZT52HC2V4WF	WX	2.2	2.6	5	85	400	1	-3.5	0.0	450	50	1
BZT52HC2V7WF	W1	2.5	2.9	5	83	500	1	-3.5	0.0	450	20	1
BZT52HC3V0WF	W2	2.8	3.2	5	95	500	1	-3.5	0.0	450	10	1
BZT52HC3V3WF	W3	3.1	3.5	5	95	500	1	-3.5	0.0	450	5	1
BZT52HC3V6WF	W4	3.4	3.8	5	95	500	1	-3.5	0.0	450	5	1
BZT52HC3V9WF	W5	3.7	4.1	5	95	500	1	-3.5	0.0	450	3	1
BZT52HC4V3WF	W6	4.0	4.6	5	95	500	1	-3.5	0.0	450	3	1
BZT52HC4V7WF	W7	4.4	5.0	5	78	500	1	-3.5	0.2	300	3	2
BZT52HC5V1WF	W8	4.8	5.4	5	60	480	1	-2.7	1.2	300	2	2
BZT52HC5V6WF	W9	5.2	6.0	5	40	400	1	-2.0	2.5	300	1	2
BZT52HC6V2WF	WA	5.8	6.6	5	10	150	1	0.4	3.7	200	3	4
BZT52HC6V8WF	WB	6.4	7.2	5	8	80	1	1.2	4.5	200	2	4
BZT52HC7V5WF	WC	7.0	7.9	5	10	80	1	2.5	5.3	150	1	5
BZT52HC8V2WF	WD	7.7	8.7	5	10	80	1	3.2	6.2	150	0.7	5
BZT52HC9V1WF	WE	8.5	9.6	5	10	100	1	3.8	7.0	150	0.5	6
BZT52HC10WF	WF	9.4	10.6	5	10	70	1	4.5	8.0	90	0.2	7
BZT52HC11WF	WG	10.4	11.6	5	10	70	1	5.4	9.0	85	0.1	8
BZT52HC12WF	WH	11.4	12.7	5	10	90	1	6.0	10.0	85	0.1	8
BZT52HC13WF	WI	12.4	14.1	5	10	110	1	7.0	11.0	80	0.1	8
BZT52HC15WF	WJ	13.8	15.6	5	15	110	1	9.2	13.0	75	0.05	10.5
BZT52HC16WF	WK	15.3	17.1	5	20	170	1	10.4	14.0	75	0.05	11.2
BZT52HC18WF	WL	16.8	19.1	5	20	170	1	12.4	16.0	70	0.05	12.6
BZT52HC20WF	WM	18.8	21.2	5	20	220	1	14.4	18.0	60	0.05	14.0
BZT52HC22WF	WN	20.8	23.3	5	25	220	1	16.4	-	60	0.05	15.4
BZT52HC24WF	WO	22.8	25.6	5	30	220	1	18.4	-	55	0.05	16.8
BZT52HC27WF	WP	25.1	28.9	2	40	250	1	21.4	-	50	0.05	18.9
BZT52HC30WF	WQ	28.0	32.0	2	40	250	1	24.4	-	50	0.05	21.0
BZT52HC33WF	WR	31.0	35.0	2	40	250	1	27.4	-	45	0.05	23.1
BZT52HC36WF	WS	34.0	38.0	2	60	250	1	30.4	-	45	0.05	25.2
BZT52HC39WF	WT	37.0	41.0	2	75	300	1	33.4	-	45	0.05	27.3
BZT52HC43WF	WU	40.0	46.0	2	80	325	1	37.6	-	40	0.05	30.1
BZT52HC47WF	WV	44.0	50.0	2	90	325	1	42.0	-	40	0.05	32.9

Notes:

^{8.} Short duration pulse test used to minimize self-heating effect. 9. f = 1kHz.







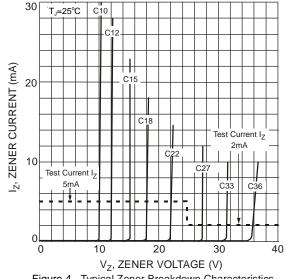
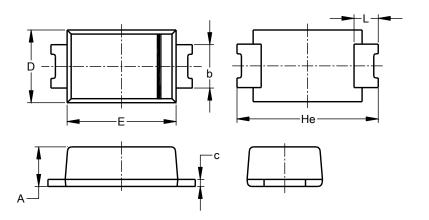


Figure 4 Typical Zener Breakdown Characteristics

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

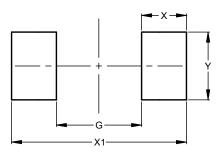


SOD123F (Type B)								
Dim	Min	Max	Тур					
Α	0.81	1.15	-					
b	0.80	1.35	-					
С	0.05	0.30	-					
D	1.70	1.90	1.80					
E	2.60	2.80	2.70					
He	3.30	3.70	3.50					
Ĺ	0.35	0.85	-					
All	Dimen	sions	in mm					



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
G	1.90
Х	1.00
X1	3.90
Υ	1.50

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